

Electronic Patent Application Fee Transmittal

Application Number:	10722174			
Filing Date:	25-Nov-2003			
Title of Invention:	On-wafer electrochemical deposition plating metrology process and apparatus			
First Named Inventor/Applicant Name:	MacKenzie King			
Filer:	Steven John Hultquist			
Attorney Docket Number:	ATMI-688			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1202	2	50	100
Independent claims in excess of 3	1201	1	210	210
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Extension - 3 months with \$120 paid	1253	1	930	930
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				2050